Components marked 'DNP' should not be populated.

Assembly Variant: 001
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01067</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<td></td>
<td>TID #: 01067</td>
<td></td>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 6/7/2017 10:10:59 AM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
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